

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:
 - a first lead having an inner portion;
 - a light emitting or receiving semiconductor chip mounted on the inner portion of the first lead;
 - a second lead having an inner portion electrically connected to the semiconductor chip;
 - and
 - a resin package for sealing the semiconductor chip together with the inner portions of the first and second leads;
 - wherein at least the semiconductor chip has outer surfaces coated with a coating film formed of amorphous fluororesin[.];
 - wherein the coating film is entirely spaced from all outer surfaces of the resin package;
 - and
 - wherein the coating film has a thickness of 5-50 μ m.
2. (Previously Presented) The semiconductor device according to claim 1, wherein the semiconductor chip is electrically connected to the inner portion of the second lead via a wire, the coating film on the outer surfaces of the semiconductor chip also covering the wire and the inner portions of the first and second leads.
3. (Original) The semiconductor device according to claim 1, wherein the amorphous fluororesin is PTFE.
4. (Canceled)
5. (Original) The semiconductor device according to claim 1, wherein the semiconductor chip is an LED chip.

6. (Original) The semiconductor device according to claim 1, wherein the resin package is formed of a transparent resin.

7-12. (Canceled)

13. (New) A semiconductor device comprising:

a first lead having an inner portion;

a semiconductor chip mounted on the inner portion of the first lead;

a second lead having an inner portion electrically connected to the semiconductor chip;

and

a resin package for sealing the semiconductor chip together with the inner portions of the first and second leads;

wherein at least the semiconductor chip has outer surfaces coated with a coating film formed of amorphous fluororesin; and

wherein the semiconductor chip is electrically connected to the inner portion of the second lead via a wire, the coating film on the outer surfaces of the semiconductor chip also covering the wire and the inner portions of the first and second leads.